

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|---|---|------------------|
| 71 | 1 | ("6271588").PN. | USPAT | 2002/06/18 09:21 |
| 72 | 1 | "5672912".PN. | USPAT | 2002/06/18 09:19 |
| 73 | 5 | ("4710798" "5172303" "5239198" "5281151" "5521435").PN. | USPAT | 2002/06/18 09:19 |
| 74 | 1 | ("6353267").PN. | USPAT | 2002/06/18 09:42 |
| 75 | 4 | ("5554887" "5757066" "5986335" "6093958").PN. | USPAT | 2002/06/18 09:23 |
| 76 | 24 | 5554887.URPN. | USPAT | 2002/06/18 09:24 |
| 77 | 4 | ("5554887" "5757066" "5986335" "6093958").PN. | USPAT | 2002/06/18 09:39 |
| 78 | 2715 | 257/787.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/06/18 09:42 |
| 79 | 313 | 257/787.ccls. and chip and circuit and (flexible or polyimide) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/06/18 09:53 |
| 80 | 234 | (257/787.ccls. and chip and circuit and (flexible or polyimide)) and (@ad<19981028) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/06/18 10:12 |
| 81 | 268 | 438/613.ccls. and (@ad<19981028) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/06/18 09:53 |
| 82 | 113 | (438/613.ccls. and (@ad<19981028)) and chip and circuit and (flexible or polyimide) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/06/18 10:07 |
| 83 | 31272 | (csp or (chip adj scale adj package) or wafer) and (polyimide or flexible or polymer) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/06/18 10:10 |
| 84 | 22545 | ((csp or (chip adj scale adj package) or wafer) and (polyimide or flexible or polymer)) and (@ad<19981028) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/06/18 10:10 |
| 85 | 30377 | wafer and (polyimide or flexible or polymer) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/06/18 10:11 |
| 86 | 6914 | wafer with (polyimide or flexible or polymer or (stress with layer)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/06/18 10:12 |
| 87 | 5220 | (wafer with (polyimide or flexible or polymer or (stress with layer))) and (@ad<19981028) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/06/18 10:13 |
| 88 | 1244 | ((wafer with (polyimide or flexible or polymer or (stress with layer))) and (@ad<19981028)) and (terminal or ball or bump or solder) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/06/18 10:15 |